



DOW™ Electrical & Telecommunications DFDA-1224 NT Low Density Polyethylene Resin

Description

DOW™ Electrical & Telecommunications DFDA-1224 NT Low Density Polyethylene Resin is a natural high molecular weight, low density polyethylene. DOW™ Electrical & Telecommunications DFDA-1224 NT Low Density Polyethylene Resin has been designed for use as a crosslinkable homopolymer for use with organic peroxides. The molecular characteristics of the product provide excellent extrusion processing, high efficiency of crosslinking, and excellent mechanical properties.

Properties¹

Physical	Nominal Value	Unit	Test Method
Density	0.923	g/cm ³	ASTM D792
Melt Mass-Flow Rate (MFR) (190°C/2.16 kg)	2.0	g/10 min	ASTM D1238
Electrical			
Volume Resistivity	> 1.0E+15	ohms·cm	ASTM D257
Dielectric Strength	> 25	kV/mm	ASTM D149
Dielectric Constant (60 Hz)	> 2.00		ASTM D150
Dissipation Factor (60 Hz)	< 1.0E-3		ASTM D2520

Extrusion Notes

DOW™ Electrical & Telecommunications DFDA-1224 NT Low Density Polyethylene Resin provides an excellent surface finish and outstanding output rates over a broad range of conditions. For optimum results, use melt extrusion temperatures in the suggested range of 248 to 266°F (120 to 130°C) when processed with organic peroxides. However, specific recommendations for processing conditions can be determined only when the application and type of processing equipment are known.

